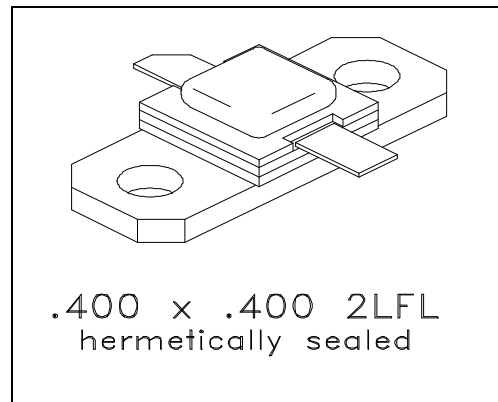


**RF & MICROWAVE TRANSISTORS  
 SPECIALITY AVIONICS/JTIDS APPLICATIONS**

**Features**

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- 15:1 VSWR CAPABILITY
- LOW RF THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- OVERLAY GEOMETRY
- METAL/CERAMIC HERMETIC PACKAGE
- $P_{OUT} = 30 \text{ W MIN. WITH } 7.8 \text{ dB Gain}$



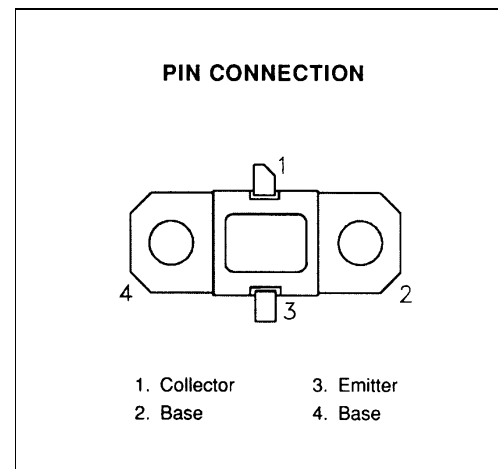
**DESCRIPTION:**

The MS2213 device is a high power Class C transistor specifically designed for JTIDS pulsed output and driver applications.

The device is capable of operation over a wide range of pulse widths, duty cycles and temperatures and is capable of withstanding 15:1 output VSWR at rated RF conditions.

Low RF thermal resistance and computerized automatic wire bonding techniques ensure high reliability and product consistency.

The MS2213 is supplied in the hermetic metal/ceramic package with internal input matching structures.



**ABSOLUTE MAXIMUM RATINGS (T<sub>case</sub> = 25°C)**

Symbol	Parameter	Value	Unit
$P_{DISS}$	Power Dissipation * (T <sub>C</sub> ≤ 85°C)	75	W
$I_C$	Device Current *	3.5	A
$V_{CC}$	Collector - Supply Voltage *	40	V
$T_J$	Junction Temperature (Pulsed RF Operation)	250	°C
$T_{STG}$	Storage Temperature	- 65 to + 200	°C

**Thermal Data**

$R_{TH(j-c)}$	Junction-Case Thermal Resistance	2.2	°C/W
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\* Applies only to rated RF amplifier operation

## ELECTRICAL SPECIFICATIONS (T<sub>case</sub> = 25°C)

### STATIC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
<b>BV<sub>CBO</sub></b>	I <sub>C</sub> = 10 mA	55	----	----	V
<b>BV<sub>EBO</sub></b>	I <sub>E</sub> = 1 mA	3.5	----	----	V
<b>BV<sub>CER</sub></b>	I <sub>C</sub> = 20 mA      R <sub>BE</sub> = 10Ω	55	----	----	V
<b>I<sub>CES</sub></b>	V <sub>CE</sub> = 35 V	----	----	5.0	mA
<b>h<sub>FE</sub></b>	V <sub>CE</sub> = 5V      I <sub>C</sub> = 1.0 A	15	----	150	----

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DataShee

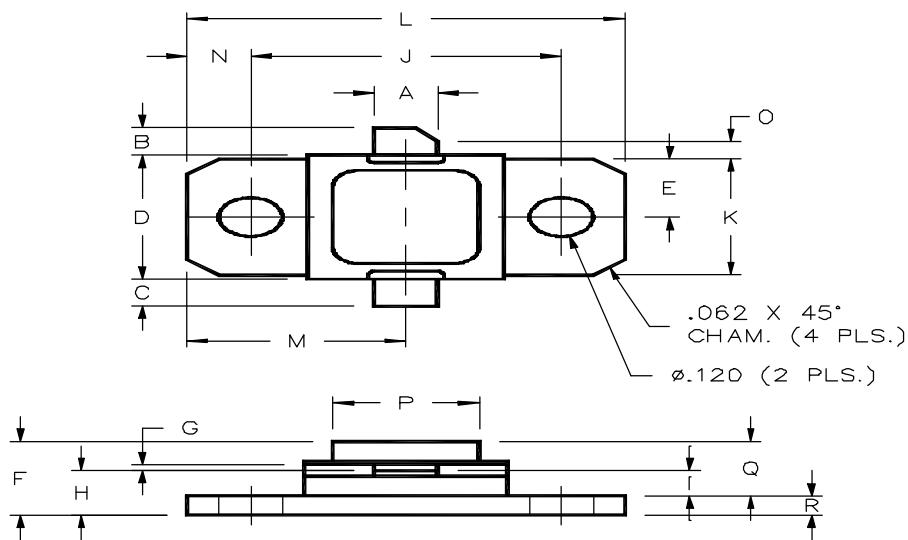
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### DYNAMIC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
<b>P<sub>OUT</sub></b>	f = 960 - 1215 MHz      P <sub>IN</sub> = 5.0 W      V <sub>CC</sub> = +35 V	30	36	----	W
<b>h<sub>c</sub></b>	f = 960 - 1215 MHz      P <sub>IN</sub> = 5.0 W      V <sub>CC</sub> = +35 V	40	45	----	%
<b>G<sub>P</sub></b>	f = 960 - 1215 MHz      P <sub>IN</sub> = 5.0 W      V <sub>CC</sub> = +35 V	7.8	8.6	----	dB

**Note:** Pulse format: 6.4 μs on 6.6 μs off, repeat for 3.3 ms, then off for 4.5125 ms.  
 Duty Cycle: Burst 49.2%, Overall 20.8%

**PACKAGE MECHANICAL DATA**



	MINIMUM INCHES/MM	MAXIMUM INCHES/MM		MINIMUM INCHES/MM	MAXIMUM INCHES/MM
A	.140/3,56		J	.650/16,51	
B	.110/2,80		K	.386/9,80	
C	.110/2,80		L	.900/22,86	
D	.395/10,03	.407/10,34	M	.450/11,43	
E	.193/4,90		N	.125/3,18	
F		.230/5,84	O	.050/1,27	
G	.003/0,08	.006/0,15	P	.405/10,29	
H	.118/3,00	.131/3,33	Q	.170/4,32	
I	.063/1,60		R	.062/1,58	